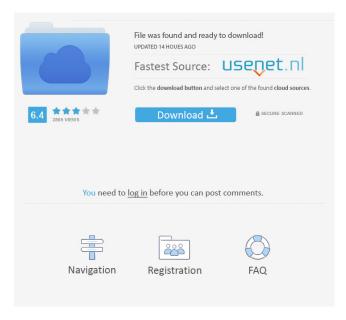


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I would like to keep the contour of the surface as simple as possible but still get a nice result (I think it's possible). I would like the end result to look like this (just for a bit of reference): I'm not sure if the "round/matte" in the second image is a trick that I missed or if it's a trick that can be used for the first image as well. The model is going to be quite big and I'm working with SketchUp. Thank you very much for the help! A: Here is a trick I used in my own boat projects: Create a plane and place it perpendicular to your hull Create a bunch of spheres and place them around your hull as far as you like. Now I needed a blackwhite transition line to fade the hull to black as it gets close to the waterline and fade back to white as the hull gets close to the water. Create a circle and extrude it a bit. Make it a bit more in the front than you'd like to get the front and back sides of the hull. Place a camera close to the front of the boat and use it to apply a black-white transition to a plane. Now the transition from hull to camera is black to white to black to white to black to white. I would probably start with a gradient fill (just to get the smooth transition you are after) and then add a texture to the fill that is a line. It looks like that would be easy to create. The only thing that is a bit more tricky is how you are going to make the line inside the hull look smooth (the line is now too thin). EDIT: here is an example of what I was talking about: 1. Field of the Invention The invention relates generally to wire bonding and, more particularly, to an ultrasonic-assisted wire bonding apparatus and method for simultaneously performing wire bonding at a plurality of bond pads on a semiconductor wafer. 2. State of the Art Wire bonding is a common technique used in the fabrication of semiconductor devices. In wire bonding, a plurality of fine electrically conductive wires are bonded at their first ends to a plurality of contact pads or leads on a semiconductor device, such as a semiconductor die, and are bonded at their second ends to 82157476af

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